

HGTG24N60D1

May 1995

24A, 600V N-Channel IGBT

Features

- 24A, 600V
- · Latch Free Operation
- Typical Fall Time <500ns
- · High Input Impedance
- . Low Conduction Loss

Description

The IGBT is a MOS gated high voltage switching device combining the best features of MOSFETs and bipolar transistors. The device has the high input impedance of a MOSFET and the low on-state conduction loss of a bipolar transistor. The much lower on-state voltage drop varies only moderately between +25°C and +150°C.

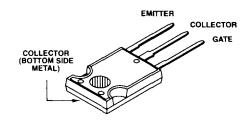
IGBTs are ideal for many high voltage switching applications operating at moderate frequencies where low conduction losses are essential, such as: AC and DC motor controls, power supplies and drivers for solenoids, relays and contactors.

PACKAGING AVAILABILITY

| PART NUMBER | PACKAGE | BRAND | | | |
|-------------|---------|----------|--|--|--|
| HGTG24N60D1 | TO-247 | G24N60D1 | | | |



JEDEC STYLE TO-247



Terminal Diagram

N-CHANNEL ENHANCEMENT MODE



Absolute Maximum Ratings T_C = +25°C, Unless Otherwise Specific

| | HGTG24N60D1 | UNITS |
|----------------------------------------------------------|------------------------------|-------|
| Collector-Emitter Voltage | 600 | V |
| Collector-Gate Voltage R _{GE} = 1MΩ | 600 | V |
| Collector Current Continuous at T _C = +25°C | 40 | Α |
| at $V_{GE} = 15V$ at $T_C = +90^{\circ}C \dots I_{C90}$ | 24 | Α |
| Collector Current Pulsed (Note 1) | 96 | Α |
| Gate-Emitter Voltage Continuous | ±25 | V |
| Switching Safe Operating Area at T _J = +150°C | 60A at 0.8 BV _{CES} | - |
| Power Dissipation Total at T _C = +25°C | 125 | W |
| Power Dissipation Derating T _C > +25°C | 1.0 | W/°C |
| Operating and Storage Junction Temperature Range | -55 to +150 | °C |
| Maximum Lead Temperature for Soldering | 260 | °C |
| (0.125 inch from case for 5s) | | |

NOTE:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

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|-----------|--------------|--------------|---------------|-------------|---------------|--------------|-----------|
| 4,364,073 | 4,417,385 | 4,430,792 | 4,443,931 | 4,466,176 | 4,516,143 | 4,532,534 | 4,567,641 |
| 4,587,713 | 4,598,461 | 4,605,948 | 4,618,872 | 4,620,211 | 4,631,564 | 4,639,754 | 4,639,762 |
| 4,641,162 | 4,644,637 | 4,682,195 | 4,684,413 | 4,694,313 | 4,717,679 | 4,743,952 | 4,783,690 |
| 4,794,432 | 4,801,986 | 4,803,533 | 4,809,045 | 4,809,047 | 4,810,665 | 4,823,176 | 4,837,606 |
| 4,860,080 | 4,883,767 | 4,888,627 | 4,890,143 | 4,901,127 | 4,904,609 | 4,933,740 | 4,963,951 |
| 4,969,027 | | | | | | | |

CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper ESD Handling Procedures. Copyright © Harris Corporation 1995

File Number 2831.3

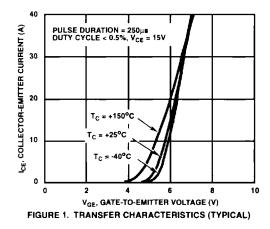
Specifications HGTG24N60D1

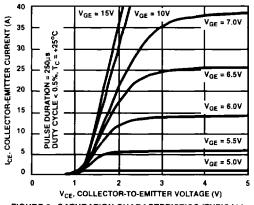
Electrical Specifications T_C = +25°C, Unless Otherwise Specified

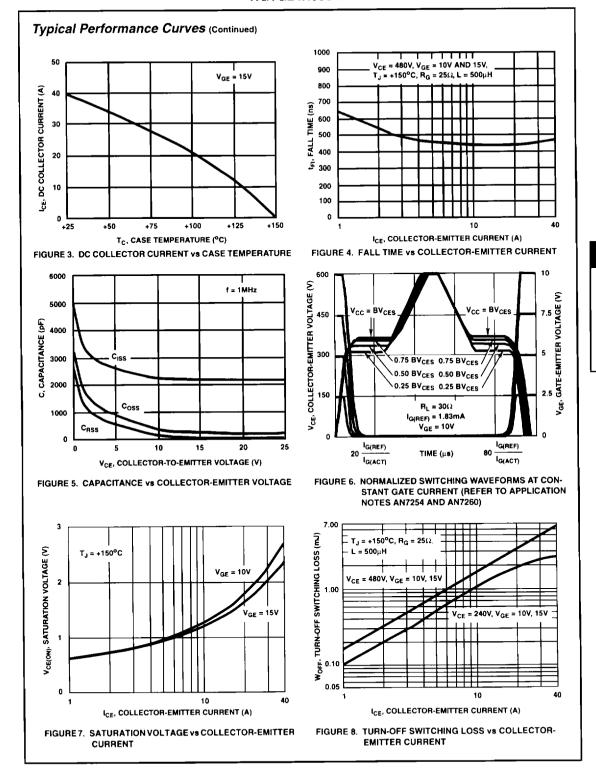
| | | | LIMITS | | | | |
|--------------------------------------|-----------------------------------|--------------------------------------------------------------------------------|-------------------------|---------|-----|------|-------|
| PARAMETERS | PARAMETERS SYMBOL TEST CONDITIONS | | DITIONS | MIN TYP | | мах | UNITS |
| Collector-Emitter Breakdown Voltage | BV _{CES} | I _C = 250μA, V _{GE} = 0V | | 600 | | - | V |
| Collector-Emitter Leakage Voltage | I _{CES} | V _{CE} = BV _{CES} | T _C = +25°C | - | - | 1.0 | mA |
| | | V _{CE} = 0.8 BV _{CES} | T _C = +125°C | - | - | 4.0 | mA |
| Collector-Emitter Saturation Voltage | V _{CE(SAT)} | I _C = I _{C90} , V _{GE} = 15V | T _C = +25°C | - | 1.7 | 2.3 | ٧ |
| | | | T _C = +125°C | | 1.9 | 2.5 | ٧ |
| Gate-Emitter Threshold Voltage | V _{GE(TH)} | t _C = 250μA, V _{CE} = V _{GE} | T _C = +25°C | 3.0 | 4.5 | 6.0 | V |
| Gate-Emitter Leakage Current | I _{GES} | V _{GE} = ±20V | | - | - | ±500 | nA |
| Gate-Emitter Plateau Voltage | V _{GEP} | I _C = I _{C90} , V _{CE} = 0.5 BV _{CES} | | - | 6.3 | - | V |
| On-State Gate Charge | Q _{G(ON)} | I _C = I _{C90} , V _{CE} = 0.5 BV _{CES} | V _{GE} = 15V | - | 120 | 155 | nC |
| | | | V _{GE} = 20V | - | 155 | 200 | nC |
| Current Turn-On Delay Time | t _{D(ON)I} | L = 500μH, I _C = I _C | | - | 100 | | ns |
| Current Rise Time | t _{RI} | $V_{GE} = 15V, T_J = +150^{\circ}C,$ $V_{CE} = 0.8 \text{ BV}_{CES}$ | | - | 150 | - | ns |
| Current Turn-Off Delay Time | t _{D(OFF)I} | 1 | - | 700 | 900 | ns | |
| Current Fall Time | t _{FI} | 1 | | | 450 | 600 | ns |
| Turn-Off Energy (Note 1) | W _{OFF} | 1 | | - | 4.3 | - | mJ |
| Thermal Resistance | R _{euc} | + | | - | - | 1.00 | °C/W |

NOTE: 1. Turn-off Energy Loss (W_{OFF}) is defined as the integral of the instantaneous power loss starting at the trailing edge of the input pulse and ending at the point where the collector current equals zero (I_{CE} = 0A) The HGTG24N60D1 was tested per JEDEC standard No. 24-1 Method for Measurement of Power Device Turn-Off Switching Loss. This test method produces the true total Turn-Off Energy Loss.

Typical Performance Curves







Typical Performance Curves (Continued)

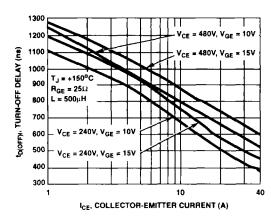


FIGURE 9. TURN-OFF DELAY VS COLLECTOR-EMITTER CURRENT

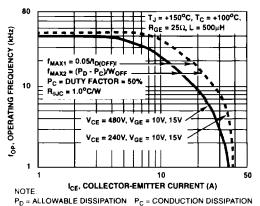


FIGURE 10. OPERATING FREQUENCY VS COLLECTOR-EMITTER CURRENT AND VOLTAGE

Operating Frequency Information

Operating frequency information for a typical device (Figure 10) is presented as a guide for estimating device performance for a specific application. Other typical frequency vs collector current (I_{CE}) plots are possible using the information shown for a typical unit in Figures 7, 8 and 9. The operating frequency plot (Figure 10) of a typical device shows f_{MAX1} or f_{MAX2} whichever is smaller at each point. The information is based on measurements of a typical device and is bounded by the maximum rated junction temperature.

 f_{MAX1} is defined by $f_{MAX1} = 0.05/f_{D(OFF)I}$. $f_{D(OFF)I}$ deadtime (the denominator) has been arbitrarily held to 10% of the onstate time for a 50% duty factor. Other definitions are possible. $f_{D(OFF)I}$ is defined as the time between the 90% point of the trailing edge of the input pulse and the point where the collector current falls to 90% of its maximum value. Device

turn-off delay can establish an additional frequency limiting condition for an application other than T_{JMAX} . $t_{D(OFF)I}$ is important when controlling output ripple under a lightly loaded condition.

 f_{MAX2} is defined by $f_{MAX2} = (P_D - P_C)/W_{OFF}$. The allowable dissipation (P_D) is defined by $P_D = (T_{JMAX} - T_C)/R_{BJC}$. The sum of device switching and conduction losses must not exceed P_D . A 50% duty factor was used (Figure 10) and the conduction losses (P_C) are approximated by $P_C = (V_{CE} \bullet I_{CE})/2$. W_{OFF} is defined as the integral of the instantaneous power loss starting at the trailing edge of the input pulse and ending at the point where the collector current equals zero $(I_{CE} = 0A)$.

The switching power loss (Figure 10) is defined as f_{MAX2} • W_{OFF} Turn-on switching losses are not included because they can be greatly influenced by external circuit conditions and components.